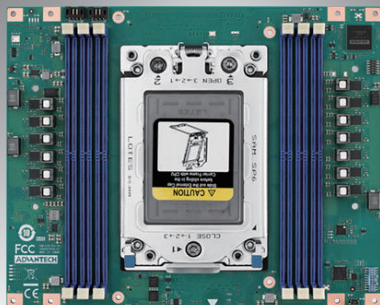


SOM-E781

AMD EPYC™ 8004 Processor COM-HPC® Server Size E module with proprietary pinout

NEW



Features

- COM-HPC® Server Size E module with proprietary pinout
- AMD EPYC™ 8004 real server grade CPU, up to 64C/200W with extreme performance
- Up to 576GB large memory size with 6x DDR5 RDIMM
- 79 lanes PCIe Gen5, includes 48 lanes CXL1.1
- Multiple I/O expansion: 2.5GbE, USB3.2 Gen1, SATA3.0
- Supports iManager, Embedded Software APIs, DeviceOn, and IPMB

Software APIs:



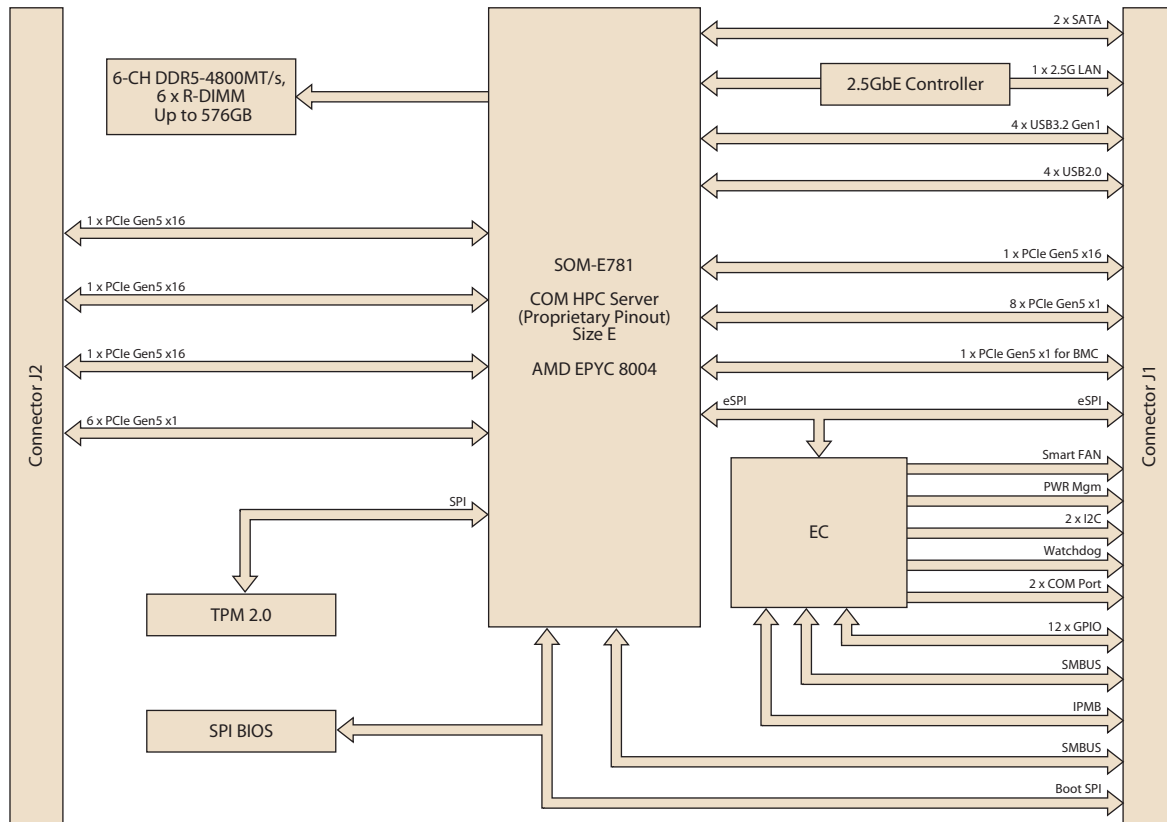
Windows Embedded

iManager WISE-DeviceOn C E FC

Specifications

Form Factor	Form Factor	COM-HPC® Size E	
	Pin-out Type	COM-HPC® Server (Proprietary Pinout)	
Processor System	CPU	8534P	8124P
	Base Frequency	2.3GHz	2.45GHz
	Max Frequency	3.1GHz	3.0GHz
	Cores	64	16
	LLC	128MB	64MB
	Default TDP	200W	125W
	Socket type	Socket SP6	
	BIOS	AMI UEFI 256Mbit	
Memory	Technology	DDR5	DDR5
	Speed	4800 MT/s	4800 MT/s
	Max. Capacity	Up to 576GB	
	Channel/Socket	6 Channel / 6 Sockets RDIMM, 1DPC	
	ECC Support	ECC and non-ECC	
Expansion	PCI Express	4 PCIe x16, 64 lanes, Gen5 (Bitfurcate to x16, x8, x4) 14 PCIe x1, 14 lanes, Gen5, extra using for KR and RSVD signals (proprietary) 1 PCIe x1, Gen 5 for BMC (COM-HPC standard), total 79 PCIe lanes	
	CXL	48 lanes CXL1.1, shared with PCIe x16	
Serial Bus	SMBus	1	
	I2C Bus	2	
Ethernet	Gigabit	Intel I226 controller ; Speed: 10M / 100M / 1000M / 2.5G speeds	
I/O	SATA3.0	2 Ports (6Gbps)	
	USB3.2 Gen1	4 Ports (5Gbps)	
	USB2.0	4 Ports (480Mbps)	
	SPI Bus	1	
	GPIO	12-bits GPIO	
	eSPI	1	
	Watchdog	65536 level, 0 ~ 65535 sec	
	COM Port	2 Ports (2-Wire)	
	TPM	TPM2.0	
	Smart Fan	2 Ports: 1 port on COM-HPC® module (4 pins); 1 port on carrier board (3 pins)	
	Type	ATX: Vin, VSB; AT: Vin	
Power	Supply Voltage	Vin: 12V (± 5%); VSB: 5V (± 5%), RTC Battery: 2.0V ~ 3.3V	
	Power Consumption (Max.)	TBD	
	Power Consumption (Idle)	TBD	
Environment	Operating Temperature	Standard: 0 ~ 60 °C (32 ~ 140 °F)	
	Storage Temperature	0 ~ 60 °C (32 ~ 140 °F)	
	Humidity	Operating: 40°C@95% relative humidity, non-condensing Storage: 60°C@95% relative humidity, non-condensing	
	Vibration Resistance	3.5 Grms	
Mechanical	Dimensions	200 x 160 mm	

Block Diagram



Ordering Information

Part No.	CPU	Core	Graphics	Base Freq.	Max. Boost Freq.	GFX HFM	GFX Burst Mode	CPU TDP	EMMC	IBEC	Thermal solution	Operating Temp.
TBD												

Any other SKUs or combination is project based support. Please contact sales for details.

Development Board

Part No.	Description
SOM-DH7000-00A1	COM-HPC Size E proprietary Dev. Board A1

Optional Accessories

Part No.	Description
TBD	QFCS
TBD	Addon fan module

Packing List

Part No.	Description	Quantity
-	SOM-E781 COM module	1

Embedded OS

OS	Part No.	Description
Windows Server	TBD	TBD